

POE-D04-00-E-18

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## **Record of change**

Date	Version	Description	page
2008.6.3	1	1. D15-00-E-09 (before) $\rightarrow$ POE-D04-00-E-01 (1 <sup>st</sup> edition)	
2008.8.22	2	1. Revised diameter	5-7
		2. Complete lead code	16-19
		3. Add last SAP code "H" for halogen and Pb free, epoxy resin	8
2008.12.12	3	1.Complete lead code of SAP P/N	3-7
		2. Page layout adjustment.	
		3. Added marking when the coating resin is Halogen and Pb free Epoxy.	
2009.8.5	4	1. Change PSA & POE logo to Walsin & POE logo.	
2011/8/24	5	1. Delete the definition about "Old Part No."	5-6
		2. Review the diameter dimension code of "Z5U 1KV 332/362" from 060 to be 070.	7
		3. Delete the Part No. of "Z5U 50V/100V 223".	
			7
2011/11/25	6	1. Review the item Y5P/Z5U/Z5V	7-8
2012/11/07	-	2. Add the Y5U temperature characteristic	4-15
2012/11/06	7	1. Revise the temp.(TCC): Y5P(-25°C to 85°C/ to 125°C) & Cap. Change( $\pm 10\% / \pm 35\%$ )	4
		2. Review the OP temp. for Y5P: Y5P: $-25^{\circ}$ C ~ $+105^{\circ}$ C (INCLUDING CAPACITOR'S	12-13
		SELF-HEATING MAX.+20°C)	
2013/5/6	8	1. Review the Lead diameter $\varphi$ from 0.60 +/-0.06mm to 0.55+/-0.05mm	6,9
		2. Review the "D $\Phi \le 6.0$ mm shall be omitted." to "D $\Phi \le 0.60$ shall be omitted."	8
		3. Review the Solderability temperature from $255(+5/-0)^{\circ}$ C to $245\pm5^{\circ}$ C .,Solderability	12
		time from 2 $\pm 0.5$ s to 5 $\pm 0.5$ s,	
2013/10/18		Review the packing specification	10
2015/8/4	10	1. Review the temperature range: Y5P(-25°C to+105°C)Change (-25°C to+125°C)	11
		2. review the high temperature loading:FOR 1000(+48/-0) HOURS AT $85 \pm 2^{\circ}C$	13
		(FOR Y5U, Z5U, Z5V) / AT $105 \pm 3$ °C (ONLY FOR Y5P) AND THEN DRIED FOR	
		$12 \sim 24$ HOURS AND MEASURED.Change FOR $1000(+48/-0)$ HOURS AT $85 \pm 2^{\circ}C$	
		(FOR Y5U, Z5U, Z5V) / AT 125 $\pm$ 3°C (ONLY FOR Y5P) AND THEN DRIED FOR	
		$12 \sim 24$ HOURS AND MEASURED.	
2015/11/5	11	1. Review the Available lead code of Lead Configuration.	5-6
		2. Modify the contents of the use of epoxy resin for 1KV products	7-8
		3. Review the Specification and test method	12-13
		4. Review 8. Cautions & notices	14
		5. Review 9. Drawing of internal structure and material list	16
2019/7/26	12	1. Review the Hole-down tape width (W0) from 11.0mm min. to 8.0mm min.	9
2021/4/22	13	1. Review the diameter dimension code of "Y5P 50V 682" from 090 to be 100.	7
2021/9/9	14	1. Delete Walsin & POE logo.	1
2022/1/8	15	1. Add "Soldering Recommendation"	17
2022/4/19	16	1. Add 8.5.3 List of substances that affect the insulation strength of coating	16
2023/6/15	17	1. The last code "B" is changed from "Epoxy Resin, Pb free" to "Halogen free and Pb	4,8
		free, epoxy resin ".	.,0
2023/1/4	18	1. Add "AF" taping type.	4,10,11

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PASSIVE SYSTEM ALLIANCE	
	Mechanical         Capacitance value vs. rated voltage, product diameter         Marking         Taping Format         Packing specification         Specification and test method         Cautions & Notices         Soldering Recommendation         Drawing of internal structure and material list:         Image: Comparison of the structure and material list image: Comparison of the structure and the s

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1.	Part numb	er for SA	P system(tota	al eighteen o	code):
	I WI V HUHHN				

<u>YP</u>	102	102	<u>K</u>	<u>060</u>	<u>B</u>	<u>20</u>	<u>C</u>	<u>5</u>	<u>B</u>
0	0	€	4	G	6	0	8	Ø	0
• Temperat	ure chara	acteristic	;:						

Code	<b>YU(Y5U)</b>	<b>YP(Y5P)</b>	ZU(Z5U)	ZV(Z5V)
Temperature range	$-25^{\circ}C$ to $+85^{\circ}C$	$-25^{\circ}C$ to $+85^{\circ}C/85^{\circ}C$ to $+125^{\circ}C$	+10°C te	o +85°C
Cap. change	-56%~+22%	$\pm 10\%$ / $\pm 55\%$	-56%~+22%	-82%~+22%

## **2** Rated voltage (Vdc) ∶

Voltage	50V	100V	500V	1000V	2000V
Code	500	101	501	102	202

## ❸Capacitance(pF) :

Capacitors (pF)	100	470	1000	2200	4700
Code	101	471	102	222	472

**O**Capacitance tolerance :  $K=\pm 10\%$   $\cdot$   $M=\pm 20\%$   $\cdot$  Z=+80%-20\%

S Nominal body diameter dimension (Ref.to page.7~8 Dφ Code spec.).

**6** Code of lead type : Please refer to Item "2.Mechanical".

### Packing mode and lead's length (identified by 2-figure code)

Taping Code	Description LIX 1/1 (S)	X
AN	Ammo / Pitch of component:12.7 mm (For D $\phi$ Code $\geq$ 120))	
AF	Ammo / Pitch of component:12.7 mm (For voltage $\ge 2KV/D\phi$ Code $\ge 060$ )	ĽШ
	PASSIVE SYSTEM ALLIANC	.e

Bulk Code	Description	
3E	Lead's length L: 3.5mm	
04	Lead's length L: 4.0mm	
4E	Lead's length L : 4.5mm	
20	Lead's length L: 20mm	nolog

### 8 Length tolerance

Code	Description	
А	$\pm 0.5$ mm(Only for short kink lead code "D / X / H")	Short lead
В	±1.0 mm	Short lead
С	Min.	Long lead
D	Taping special purpose	Taping

#### **9**Pitch

Code	Description	Code	Description
5	5.0±0.8mm (For Bulk)	7	7.5 ±1mm
5	5.0+0.8mm-0.2mm (For Taping)	0	10.0 ±1mm
2	2.5 ±0.8 mm		

#### ©Coating code

Code	Description
Р	Halogen free and Pb free, phenolic resin
А	Halogen nee and ro nee, phenone resin
В	Helegen free and Dh free anony regin
Н	Halogen free and Pb free, epoxy resin

## 2. Mechanical:

Available lead c	ode. Exam	ple:
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Available lea	d code, Exam	ple:				(unit: mm)
Lead type	SAP P/N	Pitch	Lead length (L)	Available rated	Packing	Lead configuration
Leau type	(13-17) digits	<b>(F)</b>	Leau length (L)	voltage	racking	Lead configuration
	B20C2	$2.5~\pm~0.8$	20 MIN.	50V		Davana T
	B20C5	$5.0 \pm 0.8$	20 MIN.			D max. T max.  •───•   •─→
	B20C6	$6.4 \pm 1.0$	20 MIN.		Bulk	
	B20C7	$7.5 \pm 1.0$	20 MIN.	50V,500V, 1KV,2KV		
Lead style $:$ B	B20C0	$10 \pm 1.0$	20 MIN.			
Straight long lead	BAND5	5.0 +0.8 -0.2				
	BAFD7	7.5±1.0	Taping SPEC.	1KV,2KV(Dφ≧060)	Tap. Ammo	† i⊧– F →i   L
	BAND2	2.5 ± 0.8	(Ref.to page.9~10)	50V		│ ød≠↓← │ │
	L05B2	$2.5 \pm 0.8$	$5.0 \pm 1.0$			D max. T max.
	L4EB5	$5.0 \pm 0.8$	4.5 ± 1.0			
	L05B5	$5.0 \pm 0.8$	$5.0 \pm 1.0$			
Lead style : L	L05B6	6.4 ± 1.0	$5.0 \pm 1.0$			
Straight short	L4EB7	$7.5 \pm 1.0$	$4.5 \pm 1.0$		Bulk	
lead	L05B7	$7.5 \pm 1.0$	$5.0 \pm 1.0$	50V,500V, 1KV, 2KV		
	L4EB0	$10 \pm 1.0$	$4.5 \pm 1.0$	1		╡╠╾╒╶╬╎┆║║
	L05B0	10 ± 1.0	5.0 ± 1.0			ød++
	H3EA5	5.0 ± 0.8	3.5 ± 0.5	1 A A		
	H04A5	5.0 ± 0.8	$4.0 \pm 0.5$			
	H4EB5	5.0 ± 0.8	4.5 ± 1.0	50		
	H05B5	$5.0 \pm 0.8$	5.0 ±1.0			
	H20C5	$5.0 \pm 0.8$	20 MIN.			
	H3EA7	7.5 ± 1.0	3.5 ± 0.5			D max. T max.
	H04A7	$7.5 \pm 1.0$	4.0 ± 0.5	S S	10	
Lead style : H	H4EB7	7.5 ± 1.0	4.5 ± 1.0	50V,500V, 1KV, 2KV	Bulk	( )
Inside kink	H05B7	7.5 ± 1.0	5.0 ±1.0			
lead	H20C7	7.5 ± 1.0	20MIN			
	H3EA0	$10 \pm 1.0$	3.5 ± 0.5	. COTY ON		╔┯╔┍╒╶╗╴┯╢╢
	H04A0	$10 \pm 1.0$	4.0 ± 0.5			ød++ L
	H4EB0	$10 \pm 1.0$	4.5 ± 1.0	RPORATION. M		
	H05B0	$10 \pm 1.0$	5.0 ±1.0 U	POIL.		
	H20C0	$10 \pm 1.0$	20 MIN.			
	HAND5 HAFD7	5.0 +0.8 -0.2	Taping SPEC.	50V,500V, 1KV, 2KV	Tap. Ammo	
		7.5 ± 1.0	(Ref.to page.9~10)	$1$ KV,2KV(D $\phi \ge 060$ )		
	X3EA5	5.0±0.8				D max. T max.
	X3EA7	7.5±1.0	$3.5 \pm 0.5$			
	X3EA0	10±1.0		4		
	X04A5	5.0±0.8				
Lead style : X	X04A7	7.5±1.0	$4.0 \pm 0.5$	50115001111110	Bulk	
Outside kink	X04A0	10±1.0		50V,500V, 1KV, 2KV		
lead	X05B5	5.0±0.8		1		
	X05B7	7.5±1.0	$5.0 \pm 1.0$			ød-j-ød L
	X05B7	10±1.0				
		5.0 <sup>+0.8</sup> -0.2		4		
	XAND5	-	Taping SPEC.		Tap. Ammo	
	XAFD7	$7.5 \pm 1.0$	(Ref.to page.9~10)	$1KV, 2KV(D\phi \ge 060)$		



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Lead type	SAP P/N (13-17) digits	Pitch (F)	Lead length (L)	Available rated voltage	Packing	Lead configuration
	D04A5	$5.0\pm0.8$				
	D04A7	7.5±1.0	$4.0 \pm 0.5$			D max.
	D04A0	10±1.0				
Lead style : D	D3EA5	5.0±0.8		50V,500V, 1KV, 2KV	Bulk	
	D3EA7	7.5±1.0	$3.5 \pm 0.5$			
Vertical kink lead	D3EA0	10±1.0				
lead	D20C5	$5.0 \pm 0.8$	20 MIN.	1KV, 2KV		Ø d+ +
	DAND5	5.0 +0.8 -0.2	Taping SPEC.	50V,500V, 1KV, 2KV	Т	║ ⋓ <sup>⋳</sup> ≠ <u></u> ┃ <del>╸</del> <u>↓</u> → <u></u> ┃ <del>╸┈</del>
	DAFD7	$7.5 \pm 1.0$	(Ref.to page.9~10)	1KV,2KV(Dφ≧060)	Tap. Ammo	
	M05B5	$5.0 \pm 0.8$				D max. T max.
	M05B7	7.5 ± 1.0	$5.0 \pm 1.0$			
Lead style : M	M05B0	$10 \pm 1.0$				
Double	M04B5	$5.0 \pm 0.8$				( )
outside kink	M04B7	7.5 ± 1.0		50V,500V, 1KV, 2KV	Bulk	
lead	M04B0	10 ± 1.0	4.0 ± 1.0	侵助		

 $\therefore$  Lead diameter  $\varphi = 0.55 \pm -0.05$  mm

\* Phenolic resin coating for 50V/500V product; Phenolic resin or Epoxy resin coating for 1KV product; Epoxy resin coating for 2KV product.

**\* e** (Coating **extension** on leads):

For straight lead style: 1.5mmMax when the rated voltage is 50Vdc & 100Vdc;

2.0mmMax when the rated voltage is 500Vdc and 1KVdc;

3.0mmMax when the rated voltage is 2KVdc.

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For kink lead style: not exceed the kink.

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## 3. Capacitance value vs. rated voltage, product diameter:

				1.	<b>51</b> (U.	LASS	, ц, і	empe	ratur	e:-25	°C~+8	85℃,′	Г.С.С	::±10	% &	+85°C	2~+12	' <b>5℃,</b> ′	Г.С.С	.:±55	%)					
		50V, 1	100V							500V							11	(V					21	٢V		
10	050	060	070	080	100	040	050	060	070	080	090	100	110	130	050	060	070	080	100	120	060	080	090	100	130	140
5	5.5	6.5	7.5	8.5	11.0	4.5	5.5	6.5	7.5	9.0	10.0	11.0	12.0	14.0	6.0	7.0	8.0	9.0	11.0	13.0	7.5	9.5	10.5	11.5	14.5	15.5
5	3.5	3.5	3.5	3.5	3.5	4.0	4.0	4.0	4.0	4.0	4.0	4.0	4.0	4.0	4.5	4.5	4.5	4.5	4.5	4.5	4.5	4.5	4.5	4.5	4.5	4.5
)1						101									101						101					
21						121									121						121					
51						151									151						151					
81						181									181						181					
)1						201									201						201					
21						221									221						221					
1						241									241						241					
/1						271									271						271					
31						331									331						331					
01						391									391						391					
/1						471									471						471					
61						561									561						561					
31						681										681					681					
21							821									821						821				
)2							102									102						102				
	122							122									122						122			
	152							152									152						152			
	182								182		. +							182					182			
	202								202	25	~ F	T		13	Z			202					202			
	222								222	PI				15	2			222					222			
		272							XX	272		11	15	-	X	2			272					272		
		302						1.1		302	ĺ	X	15	X	Y	1			302							
		332						K		-	332	入	IJ.	R		5			332						332	
			392				1	V		がく	392			2/	$\sim$	~ /	F,			392					392	
			472				144	XIT .	2			472			56 -	-	50			472						472
				502			1 1	NY T	20	7		502			7	-/_	C.									
				562					411			562														
					682			1	Hir -				682			DI										
					822							U		822		-										
					103									103												
	T	aping	or Bulk				$\bigcirc$	Tapi	ng or l	Bulk⊐	VE 9	SYST	∈M Bu	ilk_⊥A	NCE	T	aping	or Bul	k		Т	aping	or Bul	lk	Bı	ılk
					Р	henoli	c Resi	n							Ph	enolic	Resin	or Ep	oxy Re	esin			Epoxy	Resin		_
		J	Taping	Taping or Bulk	Taping or Bulk	822     103	822     103     Taping or Bulk	Taping or Bulk Phenolic Resi	Taping or Bulk Taping or Bulk Taping or Bulk	822       103       Taping or Bulk	Taping or Bulk Taping or Bulk Phenolic Resin	Taping or Bulk      Base Structure      Taping or Bulk      Taping or Bulk      Taping or Bulk      Taping or Bulk	822       103       Taping or Bulk       Taping or Bulk   Taping or Bulk IVE SYST	822       103       Taping or Bulk       Phenolic Resin	822     822       103     103       Taping or Bulk     Taping or Bulk IVE SYSTEM Bulk IA	822     822       103     103       Taping or Bulk     Taping or Bulk IVE SYSTEM Bulk IANCE	Baseline     Baseline     Baseline       Taping or Bulk     Taping or Bulk IVE     SYSTEM Bulk INCE       Phenolic Resin     Phenolic	Baseline     Baseline     Baseline       Taping or Bulk     Taping or Bulk IVE SYSTEM Bulk I/NCE     Taping       Phenolic Resin     Phenolic Resin	Bit Matrix     Bit Matrix       Taping or Bulk     Taping or Bulk IVE SYSTEM Bulk IANCE       Taping or Bulk     Taping or Bulk IVE SYSTEM Bulk IANCE	Barbonic Resin     State       Taping or Bulk     Taping or Bulk IVE SYSTEM Bulk INCE       Taping or Bulk     Taping or Bulk IVE SYSTEM Bulk INCE	Barbonic Resin     Barbonic Resin	Baseline     Baseline     Baseline       Taping or Bulk     Taping or Bulk IVE     SYSTEM Bulk IVE       Taping or Bulk     Taping or Bulk IVE     Taping or Bulk	Barbon     Barbon     Barbon     Barbon     Barbon       Taping or Bulk     Taping or Bulk     Taping or Bulk     Taping or Bulk     Taping or Bulk	Barbon     Barbon <td>Barbonic Resin     Barbonic Resin     Barbonic Resin     Barbonic Resin     Barbonic Resin</td> <td>Taping or Bulk     S22     Taping or Bulk     Taping or Bulk</td>	Barbonic Resin     Barbonic Resin     Barbonic Resin     Barbonic Resin     Barbonic Resin	Taping or Bulk     S22     Taping or Bulk     Taping or Bulk

T.C.						G	Z5U	(CLA	SS Ⅱ,	Temp	eratur	e: +10	°C~+8	5°C, T.	C.C.:-	+22~-5	56%)					
Rate voltage			50V,	100V			a	50	500V					1KV	51				2K	IV.		
Dq(Code)	040	050	060	070	080	100	040	050	060	070	090	050	060	070	090	100	060	070	080	090	110	130
D max. (mm)	4.5	5.5	6.5	7.5	8.5	10.5	4.5	5.5	6.5	7.5	9.5	6.0	7.0	8.0	10.0	11.0	7.5	8.5	9.5	10.5	12.5	14.5
T max. (mm)	3.5	3.5	3.5	3.5	3.5	3.5	4.0	4.0	4.0	4.0	4.0	4.5	4.5	4.5	4.5	4.5	4.5	4.5	4.5	4.5	4.5	4.5
1000								102	-CLINI	100		102	$\mathcal{O}\mathcal{N}^{\circ}$				102					
1200								122		ING	COR	122	10.				122					
1500								152		2001	001	152						152				
1800								182				182										
2000	202							202				202										
2200	222							222				222						222				
2700	272							272						272					272			
3000	302													302								
3300	332								332					332					332			
3600	362								362					362						362		
3900	392								392					392						392		
4700	472									472				472						472		
5000		502												502								
5600										562											562	
6800										682					682						682	
8200			822													822						822
10000				103							103					103						103
Packing											Taping	or Bull	ĸ								•	Bulk
Coating					Phe	nolic R	esin				Ĭ			sin or E	poxy R	lesin			Epoxy	Resin		-

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T.C.						Y	5U (C	LASS	II , Ten	nperatu	re: -25	5℃~+8	5℃, T	.C.C.:	+22~-56	<b>%</b> )					
Rate voltage		50	0V,100	V				500V					1KV					2ŀ	XV.		
Dq(Code)	050	060	070	080	100	060	070	080	090	100	050	060	070	090	110	060	070	080	090	110	140
D max. (mm)	5.5	6.5	7.5	8.5	10.5	6.5	7.5	8.5	9.5	10.5	6.0	7.0	8.0	10.0	12.0	7.5	8.5	9.5	10.5	12.5	15.5
T max. (mm)	3.5	3.5	3.5	3.5	3.5	4.0	4.0	4.0	4.0	4.0	4.5	4.5	4.5	4.5	4.5	4.5	4.5	4.5	4.5	4.5	4.5
1000						102					102					102					
1200									122					122							
1500											152						152				
2000	202																				
2200	222					222						222						222			
2700	272						272						272					272			
3000	302																				
3300	332						332						332						332		
3600	362																				
3900	392						392						392						392		
4700	472							472						472					472		
5000	502																				
5600																				562	
6800		682											682								
8200		822																			
10000			103							103					103						103
Packing		•	•		•	•	Taping	or Bull	ĸ	•	•	•		•	Bulk	k Taping or Bulk B			Bulk		
Coating					Phenoli	ic Resin	l				Phe	enolic R	lesin or	Epoxy 1	Resin			Epoxy	Resin		•

T.C.			Z5V (CLAS	SS 🛛 , Tempera	ture: +10°C~	+85°C, T.C.C.:	+22~-82%)		
Rate voltage		50V	, 100V		500V		1KV		2KV
D $\phi$ (Code)	050	060	070	080	7 080 📈	060	080	100	120
D max. (mm)	5.5	6.5	7.5	A-8.5	9.0	7.0	9.0	11.0	13.5
T max. (mm)	3.5	3.5	3.5	3.5	4.0	4.5	4.5	4.5	4.5
1000	102		17711/ 25				17		
1200	122		44						
1500	152		相対			152			
1800	182					182			
2000	202					202			
2200	222		S	PASSIVE S	STEM ALL:	222	0		
2700	272		ZIG			272	2		
3000	302		20			302			
3300	332		95 0				11		
3600	362		0	2					
3900	392			Bal			392		
4700	472		4/6	2 Chn			472		
5000			-01	Train	1051	ON HE	502		
10000		103		- CHININ	103	NIN.		103	103
20000			203		CORPON				
22000				223					
Packing					Taping or Bulk		·		
Coating			Phenolic Resin			Phenol	ic Resin or Epox	v Resin	Epoxy Resi

## 4. Marking:

Marking Remarks		$(2) \qquad \qquad$				
(1). Temp. char.	Y5P: Be mark	ed "B"; Z5U(Y5U) : Be marked "E"; Z5V : Shall be omitted				
(2). Rated capacitance	Identified by 3-Figure Code. Ex. 1000pF→"102", 4700pF→"472"					
	50V&100V	Marked with code "" under the rated capacitance.				
(3). Rated voltage	500V	No any marking under the rated capacitance.				
	1000V&2000V	Marked with code: $1000V \rightarrow "1KV"$ , $2000V \rightarrow "2KV"$				
(4). Capacitance tolerance	K=±10%(for Y	5P) \ M=±20%(for Z5U&Y5U) \ Z=+80%-20%(for Z5V)				
(5). Manufacturer's identification	Shall be marke	d as " $\lor$ ", but D $\Phi \leq 060$ shall be omitted.				
(6). Halogen and Pb free	There is a "' and Pb free Epo	marking under the code "V" when the coating resin is Halogen free bxy. (For the last code "H" and "B" of the SAP P/N)				

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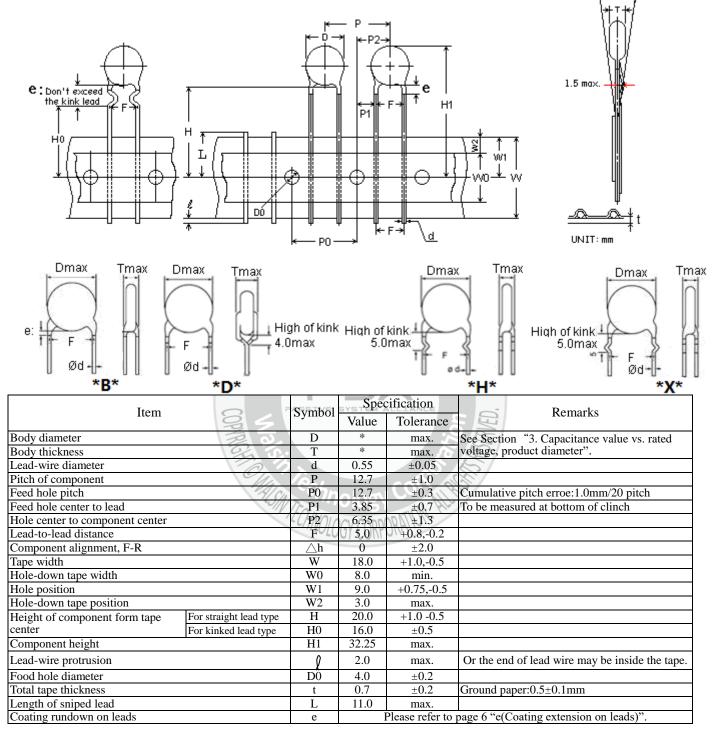
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## 5. Taping specifications:

- \* Lead spacing:  $F=5.0^{+0.8}-0.2$  (mm)
- 12.7mm pitch/lead spacing 5.0mm taping

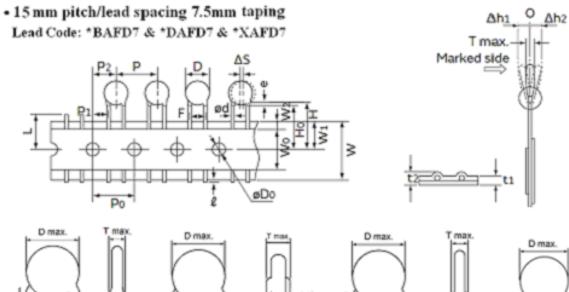
Lead code: \*BAND5 & \*DAND5 & \*HAND5 & \*XAND5

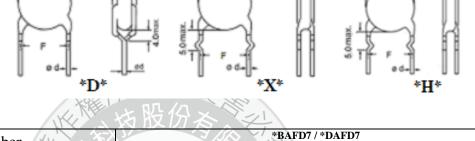


\*B\*

50V,100V,500V,1KV,2KV Hi-K CERAMIC DISC CAPACITOR FOR DOWN SIZE PRODUCT

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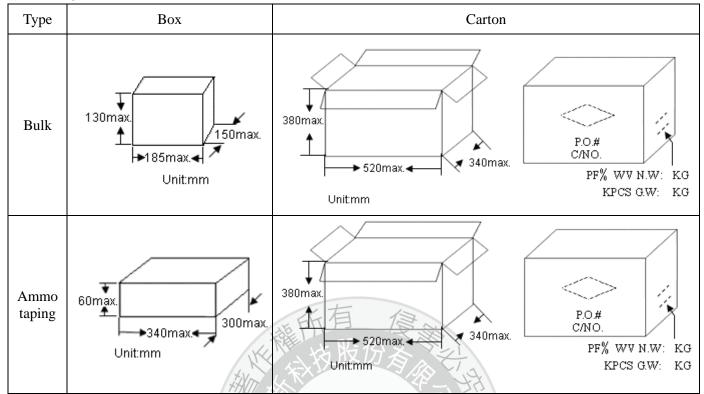
POE Part Number		*BAFD7 / *DAFD7 *HAFD7 / *XAFD7				
Item	Symbol	Dimensions (mm)				
Pitch of component	P −	15.0±1.0				
Pitch of sprocket	PO	15.0±0.3				
Lead spacing	F PASS	IVE SYSTEM ALLIANCE				
Length from hole center to component center	P2	7.5±1.5				
Length from hole center to lead	P1	3.75±1.0				
Body diameter	0,D7 >	See the "3. Capacitance value vs. Rate voltage, product diameter"				
Deviation along tape, left or right	ΔS S	0±2.0				
Carrier tape width	W	18.0 +1/-0.5				
Position of sprocket hole	W1 - 6/7	9.0±0.5				
Lead distance between the kink and center of sprocket hole	H0	18.0+2/-0 (For: *D* & *X* & *Y* lead type)				
Lead distance between the bottom of body and the center of sprocket hole	Н	20.0+1.5/-1.0 (For: *B* lead type)				
Component Height	H1	32.25Max				
Lead-Wire Protrusion length	l	2.0Max (Or the end of lead wire may be inside the tape.)				
Diameter of sprocket hole	D0	4.0±0.2				
Lead diameter	φd	$0.55 \pm 0.05$				
Total tape thickness	t1	0.6±0.3				
Total thickness, tape and lead wire	t2	1.5 max.				
Deviation across tape	∆ h	2.0 max.				
Portion to cut in case of defect	L	11.0 max.				
Hole-down tape width	W0	8.0min				
Hole-down tape distortion	W2	1.5±1.5				
Coating extension on leads	е	3.0 max for straight lead style; Not exceed the kink leads for kink lead.				
Body thickness	Т	See the "3. Capacitance value vs. Rate voltage, product diameter"				

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## 6. Packing Baggage :

6.1 Packing size:



## 6.2 Packing quantity:

Packing type	Th	in SAP P/N PASSIVE S	STEM ALLIANCE	Box)	Remark
		ANZZ	.õ2		Phenolic resin
Taping		AN	C 1.5		Epoxy resin
		AF	corp at		Epoxy resin
Packing type	Lead length	Size code of 10th to 12th in SAP P/N	MPQ (Kpcs/Bag)	Kpcs/Box	Remark
		040~070	1	3	Phenolic resin
		080~100	1	2	Phenolic resin
	Long lead (L≧ 16mm)	050~100	1	2	Epoxy resin
<b>р</b> и	1011111)	110~120	0.5	1.5	
Bulk		130~140	0.5	1	
		040~060	1	6	
	Short lead	070~080	1	4	
	(L< 090~100	1	3		
		110~140	1	2	

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### 7. Specification and test method:

7.1 SCOPE: THIS SPECIFICATION APPLIES TO HI-K CERAMIC TYPE CAPACITOR.

7.2 TEST CONDITIONS :

UNLESS OTHERWISE SPECIFIED, ALL TESTS SHALL BE OPERATED AT THE STANDARD TEST CONDITIONS OF TEMPERATURE 5°C TO 35°C AND RELATIVE HUMIDITY 45% TO 85%. WHEN FAILS A TEST, RETEST BE OPERATED AT THE CONDITIONS OF TEMPERATURE 25°C  $\pm$  2°C, RELATIVE HUMIDITY OF 60% TO 70% AND BAROMETRIC PRESSURE 860 TO 1060 MBAR.

7.3 HANDLE PROCEDURE : TO AVOID UNEXPECTED TESTING RESULTS FROM OCCURRING, THE TESTED CAPACITOR MUST BE KEPT AT ROOM TEMPERATURE FOR AT LEAST 30 MINUTES AND COMPLETELY DISCHARGED.

7.4 TEST ITEMS :

ITEM	POST-TEST REQUIREMENTS	TESTING PROCEDURE				
APPEARANCE STRUCTURE SIZE	NO ABNORMALITIES	AS STATED IN SECTION 3.				
MARKING		AS STATED IN SECTION 4				
	BETWEEN TERMINALS: NO ABNORMALITIES	<ul> <li>A. BELOW 1KV: 250% RATED VOLTAGE WITH 50mA MAX. CHARGING CURRENT FOR 1~5 SEC.</li> <li>B. 1KV &amp; ABOVE: 200% RATED VOLTAGE WITH 50mA MAX. CHARGING CURRENT FOR 1~5 SEC.</li> </ul>				
WITHSTAND VOLTAGE	BETWEEN TERMINAL AND	SMALL METALLIC BALLS WITH 1mm DIAMETERS SHALL BE PUT ON A VESSEL AND THE TEST CAPACITOR SHALL BE SUBMERGED EXCEPT 2mm FROM THE TOP OF ITS COMPONENT BODY.				
	ENCLOSURE : NO ABNORMALITIES	THE TEST VOLTAGE SHALL BE APPLIED BETWEEN THE SHORT-CIRCUITED TERMINALS AND THE METALLIC BALLS.				
	GH SI	(APPLY 1.3KV DC VOLTAGE BETWEEN TERMINALS AND ENCLOSURE FOR $1 \sim 5$ SEC)				
INSULATION RESISTANCE	10000 MΩ MIN	INSULATION RESISTANCE SHALL BE MEASURED AT 60±5 SECONDS AFTER RATED VOLTAGE APPLIED. RATED VOLTAGE :100V =100V 500V & ABOVE = 500V				
CAPACITANCE	TOLERANCE : K : ±10% M : ±20% Z : +80-20%	TESTING FREQUENCY: 1 KHZ $\pm$ 20% TESTING TEMPERATURE: 25 $\pm$ 2°C TESTING VOLTAGE: 1.0Vrms				
OPERATING TEMPERATURE RANGE	$Y5P: -25^{\circ}C \sim +125^{\circ}C$ $Y5U: -25^{\circ}C \sim +85^{\circ}C$ $Z5U \& Z5V: +10^{\circ}C \sim +85^{\circ}C$					
TEMPERATURE RANGE	Y5P : $-25^{\circ}$ C $+125^{\circ}$ C (INCLUDINY5U: $-25^{\circ}$ C $+85^{\circ}$ CZ5U & Z5V: $+10^{\circ}$ C $-+85^{\circ}$ C	NG CAPACITOR'S SELF-HEATING MAX.+20 $^{\circ}$ C)				
DISSIPATION FACTOR (D.F)	Y5P : BELOW 2.5% Z5U & Y5U : BELOW 2.5% Z5V : BELOW 5.0%	AS ABOVE STIPULATION OF CAPACITANCE				

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ITEM	POST-TEST REQUIREMENTS	TESTING PROCEDURE						
TEMPERATURE CHARACTERISTIC	CAP. CHANGE : Y5P : WITHIN ± 10%(-25°C to +85°C) & WITHIN ± 55%(85°C to +125°C) Z5U & Y5U : WITHIN -56,+22% Z5V : WITHIN -82,+22%	CAPACITANCE SHALL BE MEASURED AT 25°C. AND CLASSIFIED AS CAP. CHANGE : CLASS Y5P : $-25^{\circ}$ C ~ $+125^{\circ}$ C CLASS Y5U : $-25^{\circ}$ C ~ $+85^{\circ}$ C CLASS Z5U&Z5V : $+10^{\circ}$ C ~ $+85^{\circ}$ C Pre-treatment: Capacitor shall be stored at $125\pm3^{\circ}$ C for 1 hour.then placed at % 1 room condition for 24±2 hours						
TERMINAL STRENGTH	TENSILE STRENGTH : NO BREAKDOWN	WIRE DIA.0.5 M/M, LOADING WEIGHT 0.5KG FOR 10±1 SECONDS WIRE DIA.0.6 M/M, LOADING WEIGHT 1.0KG FOR 10±1 SECONDS						
	BENDING STRENGTH : NO BREAKDOWN	WIRE DIA.0.5 M/M, LOADING WEIGHT 0.25 KG WIRE DIA.0.6 M/M, LOADING WEIGHT 0.5 KG (BENDING BACK AND FORTH 90 DEGREE TWICE)						
SOLDERABILITY	LEAD WIRE SHALL BE SOLDERED OVER 3/4 OF THE CIRCUMFERENTIAL DIRECTION.	TO COMPLY WITH JIS-C-5102 8.4 SOLDER TEMPERATURE 245±5°C AND DIPPING TIME 5±0.5 SECONDS. FLUX : WEIGHT RATIO OF POSIN 25%						
	APPEARANCE : NO ABNORMALITIES	LEAD WIRE OR TERMINALS SHALL IMMERSE UP TO 2.0 M/M FORM BODY						
	CAP. CHANGE : Y5P : ±5% MAX Z5U & Y5U : ±15% MAX Z5V : ±20% MAX	<ul> <li>(A) BODY DIA. ≤5.0mm: INTO THE MOLTEN SOLDER OF WHICH TEMPERATURE: 260(+5/-0)°C FOR 3.0±0.5 SECONDS.</li> <li>(B) BODY DIA. &gt;5.0mm: INTO THE MOLTEN SOLDER OF WHICH TEMPERATURE 260(+5/-0)°C FOR 5~10 SECONDS.</li> </ul>						
SOLDERING HEAT RESISTANCE	WITHSTAND VOLTAGE: (BETWEEN TERMINALS) NO ABNORMALITIES	THEN LEAVE AT STANDARD TEST CONDITIONS FOR 24±2 HOURS, THEN MEASURED. * WHEN SOLDERING CAPACITOR WITH A SOLDERING IRON, IT SHOULD BE PERFORMED IN FOLLOWING CONDITIONS. TEMPERATURE OF IRON-TIP: 350~400 °C SOLDERING IRON WATTAGE : 50W MAX. SOLDERING TIME : 3.5 SEC. MAX.						
HUMIDITY CHARACTERISTIC (STABLE SITUATION)	APPEARANCE: NO ABNORMALITIES CAP. CHANGE : Y5P : ± 15% MAX Z5U & Y5U : ± 20% MAX Z5V : ± 30% MAX D.F. Y5P : 5% MAX	CAPACITORS SHALL BE SUBJECTED TO A RELATIVE HUMIDITY OF 90 $\sim$ 95% AT 40±2°C FOR 500(+24/-0) HOURS. THEN DRIED FOR 1 $\sim$ 2 HOURS AND MEASURED.						
	Z5U & Y5U: 5% MAX Z5V : 7.5% MAX INSULATION RESISTANCE : 1000MΩ MIN.							

X1"room condition" Temperature:15~35, Relative humidity: 45~75%, Atmospheric pressure:86~106kPa

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ITEM	POST-TEST REQUIREMENTS	TESTING PROCEDURE
	APPEARANCE:	CAPACITORS SHALL BE SUBJECTED TO A RELATIVE
	NO ABNORAMLITIES	HUMIDITY OF 90 $\sim$ 95% AT 40 ± 2°C FOR 500(+24/-0)
	CAP. CHANGE :	HOURS WITH RATED VOLTAGE APPLIED WITH 50mA
	Y5P: ±15% MAX	MAX., THEN DRIED FOR $1 \sim 2$ HOURS AND MEASURED.
	Z5U & Y5U: ±20% MAX	Pre-treatment:
HUMIDITY	Z5V: ±30% MAX	Capacitor shall be stored at $125\pm3^{\circ}$ for 1 hour. then placed at $\%$
LOADING	D.F.	1room condition for 24±2hours
	Y5P: 5% MAX	
	Z5U & Y5U : 5% MAX	
	Z5V : 7.5% MAX	
	INSULATION RESISTANCE	
	500 MΩ MIN.	
	APPEARANCE :	CAPACITORS SHALL BE SUBJECTED TO A TEST OF
	NO ABNORMALITIES	(A) BELOW 1KV: 200% RATED VOLTAGE WITH 50mA
	CAP. CHANGE :	MAX.
	Y5P: ±15% MAX	(B) 1KV & ABOVE: 150% RATED VOLTAGE WITH 50mA
	Z5U & Y5U: ±20% MAX	MAX.
HIGH	Z5V : ±30% MAX	FOR 1000(+48/-0) HOURS AT 85 $\pm$ 2°C (FOR Y5U, Z5U,
TEMPERATURE	D.F.	Z5V) / AT 125 $\pm$ 3°C (ONLY FOR Y5P) AND THEN DRIED
LOADING	Y5P:4% MAX	FOR 12 $\sim$ 24 HOURS AND MEASURED.
	Z5U & Y5U: 4% MAX	Pre-treatment: S
	Z5V : 7.5% MAX	Capacitor shall be stored at $125\pm3^{\circ}$ for 1 hour. then placed at $\times$
	INSULATION RESISTANCE :	1room condition for 24±2hours
	1000 MΩ MIN.	COTO SE
	APPEARANCE :	CAPACITORS SHALL BE SUBJECTED TO:
	NO ABNORMALITIES	$-25\pm3^{\circ}\mathbb{C}(30\pm3\min) \rightarrow 25^{\circ}\mathbb{C}(3\min) \rightarrow 85\pm3^{\circ}\mathbb{C}(30\pm3\min) \rightarrow$
	CAP. CHANGE :	25°C (3min) FOR 5 CYCLE.
	Y5P: ±15% MAX	Pre-treatment:
	Z5U & Y5U: ±20% MAX	Capacitor shall be stored at $125\pm3^{\circ}$ for 1 hour, then placed at $\%$
TEMPERATURE	Z5V : ±30% MAX	1room condition for 24±2hours
CYCLING	D.F.	
	Y5P: 5% MAX	
	Z5U & Y5U: 5% MAX	
	Z5V : 7.5% MAX	
	INSULATION RESISTANCE :	
	1000 MΩ MIN.	

X1"room condition" Temperature:15~35, Relative humidity: 45~75%, Atmospheric pressure:86~106kPa

### 8. Cautions & notices:

**\***Application: DC or Low frequency High Voltage circuits.

As coupling and decoupling capacitors for such application where higher losses and a reduced capacitance stability are required.

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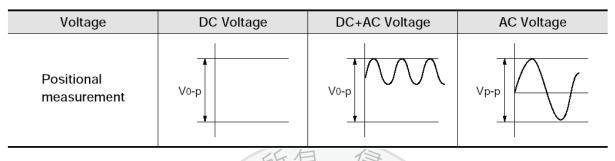
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### 8.1. Caution (Rating)

#### I. Operating Voltage

When DC-rated capacitors are to be used in AC or ripple current circuits, be sure to maintain the Vp-p value of the applied voltage or the Vo-p which contains DC bias within the rated voltage range.

When the voltage is applied to the circuit, starting or stopping may generate irregular voltage for a transit period because of resonance or switching. Be sure to use a capacitor with a rated voltage range that includes these irregular voltages.



## II. Operating Temperature and Self-generated Heat

Keep the surface temperature of a capacitor below the upper limit of its rated operating temperature range. Be sure to take into account the heat generated by the capacitor itself. When the capacitor is used in a high frequency current, pulse current or similar current, it may self-generate heat due to dielectric loss. The frequency of the applied sine wave voltage should be less than 150Hz. The applied voltage load (\*) should be such that the capacitor's self-generated heat is within 20°C at an atmosphere temperature of 25°C. When measuring, use a thermocouple of small thermal capacity-K of ø0.1mm in conditions where the capacitor is not affected by radiant heat from other components or surrounding ambient fluctuations. Excessive heat may lead to deterioration of the capacitor's characteristics and reliability. (Never attempt to perform measurement with the cooling fan running. Otherwise, accurate measurement cannot be ensured.)

## III. Fail-Safe

When capacitor is broken, failure may result in a short circuit. Be sure to provide an appropriate fail-safe function like a fuse on your product if failure would follow an electric shock, fire or fume.

## 8.2. Caution (Storage and operating condition)

## I. Operating and storage environment

The insulating coating of capacitors does not form a perfect seal; therefore, do not use or store capacitors in a corrosive atmosphere, especially where chloride gas, sulfide gas, acid, alkali, salt or the like are present. And avoid exposure to moisture. Before cleaning, bonding or molding this product, verify that these processes do not affect product quality by testing the performance of a cleaned, bonded or molded product in the intended equipment. Store the capacitors where the temperature and relative humidity do not exceed -10 to 40 degrees centigrade and 15 to 85 % for 6 months maximum and use within the period after receiving the capacitors.

FAILURE TO FOLLOW THE ABOVE CAUTIONS MAY RESULT, WORST CASE, IN A SHORT CIRCUIT AND CAUSE FUMING OR PARTIAL DISPERSION WHEN THE PRODUCT IS USED.

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#### 8.3. Caution (Soldering and Mounting)

#### I. Vibration and impact

Do not expose a capacitor or its leads to excessive shock or vibration during use.

#### II. Soldering

When soldering this product to a PCB/PWB, do not exceed the solder heat resistance specification of the capacitor.

Subjecting this product to excessive heating could melt the internal junction solder and may result in thermal shocks that can

crack the ceramic element. When soldering capacitor with a soldering iron, it should be performed in following conditions.

Temperature of iron-tip: 400 degrees C. max.

Soldering iron wattage : 50W max.

Soldering time : 3.5 sec. max.

FAILURE TO FOLLOW THE ABOVE CAUTIONS MAY RESULT, WORST CASE, IN A SHORT CIRCUIT AND CAUSE FUMING OR PARTIAL DISPERSION WHEN THE PRODUCT IS USED.

#### 8.4. Caution (Handling)

Vibration and impact

Do not expose a capacitor or its leads to excessive shock or vibration during use.

FAILURE TO FOLLOW THE ABOVE CAUTIONS MAY RESULT, WORST CASE, IN A SHORT CIRCUIT AND CAUSE FUMING OR PARTIAL DISPERSION WHEN THE PRDUCT IS USED.

#### 8.5. Notice

8.5.1. Notice (Soldering and Mounting)

Cleaning (ultrasonic cleaning)

To perform ultrasonic cleaning, observe the following conditions.

Rinse bath capacity : Output of 20 watts per liter or less.

Rinsing time : 5 min. maximum.

Do not vibrate the PCB/PWB directly.

Excessive ultrasonic cleaning may lead to fatigue destruction of the lead wires.

#### 8.5.2. Notice (Rating)

Capacitance change of capacitor

#### Class 2 series:

Capacitors have an aging characteristic, whereby the capacitor continually decreases its capacitance slightly if the capacitor is left on for a long time. Moreover, capacitance might change greatly depending on the surrounding temperature or an applied voltage. So, it is not likely to be suitable for use in a time constant circuit. Please contact us if you need detailed information.

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8.5.3 List of substances that affect the insulation strength of coating :

Resin solvent

Category	Model			
Ketone	Acetone	Butanone	Cyclohexanone	
Esters	Ethyl acetate	Dibutyl phthalate		
Chlorinated hydrocarbons	Dichloromethane			

Resin thinner

Category		Model	
		HK-66 (Alkyl glycidyl ether)	
	Simple function group	501 (Butyl glycidyl ether)	
Reactive diluentactivated thinner		690 (Phenyl Glycidyl Ether )	
		AGE (C12-14Aliphatic Polyalcohol Glycidyl	
		Ether)	
		692 (Benzyl Glycidyl Ether)	
Reactive undernactivated unmer	Two functional groups	D-678 (Neopentyl glycol diglycidyl ether)	
		622 (1,4-Butanediol diglycidyl ether)	
		669 (Ethylene glycol diglycidyl ether)	
		X-632 (Polypropylene glycol diglycidyl ether)	
		X-652 (1,6-Hexadiol diglycidyl ether)	
		D-691Epoxypropane o-methylphenyl ether	
	长楼 枯股伤	Anhydrous ethanol	Toluene
4.5	N XXX IIII	Ethyl acetate	Dimethylbenzene
Non-activated th	inner	Dimethyl formamide	Butyl acetate
		Acetone	Styrene
		Polyol	Benzyl alcohol

Note: The above substances should not contact the coating of the product body, otherwise it will affect the insulation strength of the product

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#### 9. Soldering Recommendation:

#### 9.1 Wave Soldering Profile:

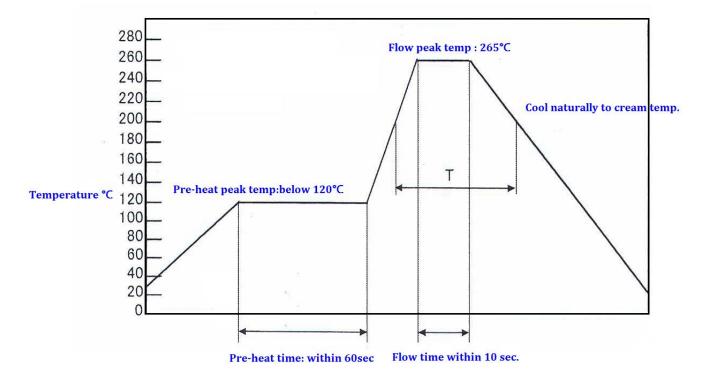
- Temperature conditions of the flow is recommended as shown in the chart
- Must implement the pre-heat
- Maximum peak flow temperature is recommended  $265^{\circ}$ C
- Time "T" implement in the chart recommended within 20 sec. it temperature exceed 200°C

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• Take care with the flow solder not to touch the capacitor body directly at mounting



#### Chart to show flow recommended temp



#### 9.2 Recommended Reworking Conditions with Soldering Iron :

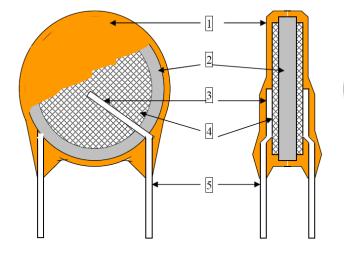
- Temperature of iron-tip: 400 degrees C. max.
- Soldering iron wattage: 50W max.
- Soldering time: 3.5 sec. max.
- Distance from coating body: 2 mm (min.)

9.3 Reflow-Soldering : Lead Ceramic Cap. should not be soldered by reflow-soldering.

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## 10. Drawing of internal structure and material list:



(phenolic resin)

(epoxy resin)

NO.	部位	材質	与这个一構成部份	供應商				
	Part name	Material	Component	Vendor				
1 Insula	Inculation Coating	Phenolic resin	Phenolic resin, Filler, Pigment	Namics				
	Insulation Coating	Epoxy resin	Epoxy resin, SiO2, TiO2	Kai Hua				
		171/	Δ	Hua Xing				
2 Dieleo	Dielectric Element		BaTiO3	Wang Feng				
			MEC MEC	Fenghua				
3 So	Solder	Tin-silver	Sn97.5-Ag2.5	Huajun				
	Soluel			Haili				
4	Electrodes	Ag	Silver,Glass frit	Daejoo				
	Lieculoues			Xinguang				
5	Leads wire	Tinned copper	Substrate metal:Fe&Cu	Hengtai				
		clad steel wire	Surface plating:Sn 100%	Wuhu Taililai				

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